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Nucleation, grain orientations, and microstructure of Sn-3Ag-0.5Cu soldered on cobalt substrates

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Abstract

The potential of cobalt substrates to control the microstructure of 550 μ m Sn-3Ag-0.5Cu ball grid array (BGA) joints is explored. It is shown that cobalt substrates give a small and reproducible nucleation undercooling for tin and prevent the formation of large primary Ag₃Sn blades and Cu₆Sn₅ rods. β Sn dendrites grew from the CoSn₃ reaction layer and the β Sn grains are shown to inherit their orientation from the CoSn₃ layer due to heterogeneous nucleation with the following orientation relationship: $(100)_{Sn}||(100)_{CoSn3}$ with $[001]_{Sn}||[001]_{CoSn3}$. Changes in the dendrite and eutectic microstructure are shown to be caused by the reduced nucleation undercooling for β Sn and the altered solidification path due to cobalt substrate dissolution.

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